## **BUV21**

# **SWITCHMODE™** Series NPN Silicon Power Transistor

This device is designed for high speed, high current, high power applications.

#### **Features**

• High DC Current Gain:

 $h_{FE} \min = 20 \text{ at } I_C = 12 \text{ A}$ 

• Low  $V_{CE(sat)}$ ,  $V_{CE(sat)}$ 

 $max = 0.6 \text{ V at } I_C = 8 \text{ A}$ 

• Very Fast Switching Times:

TF max =  $0.4 \mu s$  at  $I_C = 25 A$ 

• Pb-Free Package is Available\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO(SUS)</sub>	200	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	250	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	7	Vdc
Collector–Emitter Voltage (V <sub>BE</sub> = -1.5 V)	V <sub>CEX</sub>	250	Vdc
Collector–Emitter Voltage ( $R_{BE} = 100 \Omega$ )	V <sub>CER</sub>	240	Vdc
Collector-Current - Continuous - Peak (PW ≤ 10 ms)	I <sub>C</sub>	40 50	Adc Apk
Base-Current Continuous	I <sub>B</sub>	8	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C	P <sub>D</sub>	250	W
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to 200	°C

#### THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	θЈС	0.7	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



### ON Semiconductor®

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# 40 AMPERES NPN SILICON POWER METAL TRANSISTOR 200 VOLTS – 250 WATTS



TO-204AE (TO-3) CASE 197A

#### **MARKING DIAGRAM**



BUV21 = Device Code G = Pb-Free Package A = Assembly Location

Y = Year WW = Work Week MEX = Country of Origin

#### **ORDERING INFORMATION**

Device	Package	Shipping
BUV21	TO-204	100 Units / Tray
BUV21G	TO-204 (Pb-Free)	100 Units / Tray

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **BUV21**

### **ELECTRICAL CHARACTERISTICS**

	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS (Note	1)				
Collector–Emitter Sustaining Vo (I <sub>C</sub> = 200 mA, I <sub>B</sub> = 0, L = 25 m	V <sub>CEO(sus)</sub>	200		Vdc	
Collector Cutoff Current at Reve ( $V_{CE} = 250 \text{ V}, V_{BE} = -1.5 \text{ V}$ )( $V_{CE} = 250 \text{ V}, V_{BE} = -1.5 \text{ V}, T$	I <sub>CEX</sub>		3.0 12.0	mAdc	
Collector–Emitter Cutoff Current (V <sub>CE</sub> = 160 V)	I <sub>CEO</sub>		3.0	mAdc	
Emitter–Base Reverse Voltage (I <sub>E</sub> = 50 mA)	V <sub>EBO</sub>	7		V	
Emitter–Cutoff Current (V <sub>EB</sub> = 5 V)	I <sub>EBO</sub>		1.0	mAdc	
SECOND BREAKDOWN		•	•	•	•
Second Breakdown Collector Co (V <sub>CE</sub> = 20 V, t = 1 s) (V <sub>CE</sub> = 140 V, t = 1 s)	I <sub>S/b</sub>	12 0.15		Adc	
ON CHARACTERISTICS (Note 1	1)	1			
DC Current Gain (I <sub>C</sub> = 12 A, V <sub>CE</sub> = 2 V) (I <sub>C</sub> = 25 A, V <sub>CE</sub> = 4 V)	h <sub>FE</sub>	20 10	60		
Collector–Emitter Saturation Vol ( $I_C = 12 \text{ A}, I_B = 1.2 \text{ A}$ ) ( $I_C = 25 \text{ A}, I_B = 3 \text{ A}$ )	V <sub>CE(sat)</sub>		0.6 1.5	Vdc	
Base–Emitter Saturation Voltage $(I_C = 25 \text{ A}, I_B = 3 \text{ A})$	V <sub>BE(sat)</sub>		1.5	Vdc	
DYNAMIC CHARACTERISTICS		<u>'</u>			1
Current Gain – Bandwidth Produ (V <sub>CE</sub> = 15 V, I <sub>C</sub> = 2 A, f = 4 MI	f <sub>T</sub>	8.0		MHz	
SWITCHING CHARACTERISTIC	S (Resistive Load)	•	-	•	•
Turn-on Time		t <sub>on</sub>		1.0	μs
Storage Time	me $(I_C = 25 \text{ A}, I_{B1} = I_{B2} = 3 \text{ A}, V_{CC} = 100 \text{ V}, R_C = 4 \Omega)$			1.8	1
Fall Time	-66 .30 4, 136 - 122)	t <sub>f</sub>		0.4	1

<sup>1.</sup> Pulse Test: Pulse Width  $\leq 300 \,\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

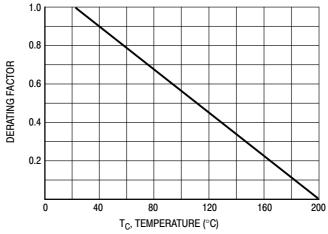


Figure 1. Power Derating

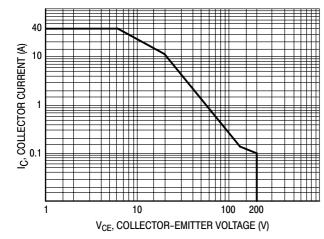


Figure 2. Active Region Safe Operating Area

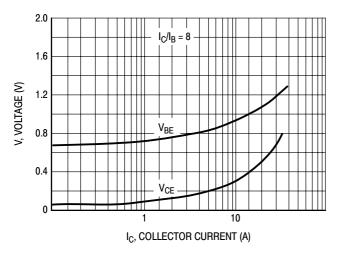


Figure 3. "On" Voltages

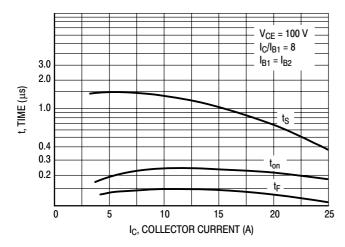


Figure 5. Resistive Switching Performance

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 2 is based on  $T_C = 25^{\circ}C$ ,  $T_{J(pk)}$  is variable depending on power level. Second breakdown limitations do not derate the same as thermal limitations.

At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

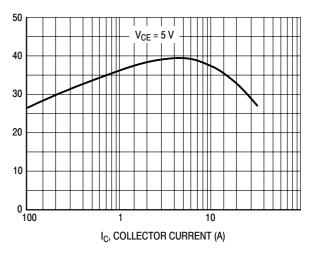
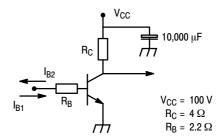


Figure 4. DC Current Gain



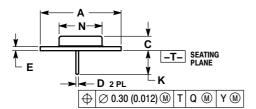
R<sub>C</sub> - R<sub>B</sub>: Non inductive resistances

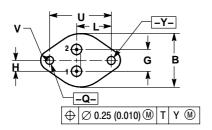
Figure 6. Switching Times Test Circuit

#### **BUV21**

#### PACKAGE DIMENSIONS

**TO-204 (TO-3)** CASE 197A-05 ISSUE K





#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

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	INCHES MILLIMETE			IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	1.530 REF		38.86 REF		
В	0.990	1.050	25.15	26.67	
C	0.250	0.335	6.35	8.51	
D	0.057	0.063	1.45	1.60	
E	0.060	0.070	1.53	1.77	
G	0.430 BSC		10.92 BSC		
Н	0.215 BSC		5.46 BSC		
K	0.440	0.480	11.18	12.19	
L	0.665 BSC		16.89 BSC		
N	0.760	0.830	19.31	21.08	
Q	0.151	0.165	3.84	4.19	
U	1.187 BSC		30.15 BSC		
٧	0.131	0.188	3.33	4.77	

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